



Integrated Device Technology, Inc.
2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **L0203-09R2** DATE: 8/16/2004
Product Affected: Please see attachment for the product list

MEANS OF DISTINGUISHING CHANGED DEVICES:

- Product Mark
- Back Mark
- Date Code See attached list for New Steppings
- Other

Date Effective: August 16, 2004

Contact: Bimla Paul	Attachment: <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No
Title: Quality Assurance Manager	
Phone #: (408)-654-6419	
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DESCRIPTION AND PURPOSE OF CHANGE:

- Die Technology To upgrade the Fabrication Process Technologies on selected Logic products, and transfer wafer fab production from Salinas, California (Fab 2) to Hillsboro, Oregon (Fab 4).
 - Wafer Fabrication Process
 - Assembly Process There is no change in data sheet specifications.
 - Equipment
 - Material PCN Revision 1:
 - Testing Due to declined market and process evolution, status of selected devices has been revised. Please refer to the column "Revised Status" in the attachment for details.
 - Manufacturing Site
 - Data Sheet
 - Other PCN Revision 2:
- Selected products will not be transferred to Fab 4 due to sufficient existing Fab 2 inventory.**
Selected products will be transferred to stepping "Z" in addition to stepping "PB".

RELIABILITY/QUALIFICATION SUMMARY:

Please see attachment for qualification data.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.

IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____	<input type="checkbox"/> <i>Approval for shipments prior to effective date.</i>
Name/Date: _____	E-Mail Address: _____
Title: _____	Phone# /Fax# : _____

CUSTOMER COMMENTS: _____

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____ DATE: _____



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PCN Type: Process Technology Change & Fab Site Change

Data Sheet Change: None

Detail of Change: PCN # L0203-09 was previously issued on 4/15/02 to notify customers about upgrading the Fabrication Process Technologies on selected Logic products, and transfer wafer fab production from Salinas, California (Fab 2) to Hillsboro, Oregon (Fab 4). There is no change in data sheet specifications.

Revision 1: The products listed in the column labeled "Revised Status" are affected by the PCN as follow:

- i. Three devices will be discontinued in October 2003 per PDN # L-02-04 due to declined market.
- ii. Selected products that were previously specified as KB will be transferred to PB stepping.
- iii. Selected products that were previously specified as KB will be transferred to Z stepping
- iv. Selected products that are on hold due to existing inventory.

Revision 2:

- i. Selected products that were listed on hold per PCN # L0203-09R1 will not be transferred to Fab 4 due to sufficient existing Fab 2 inventory.
- ii. Selected products will be transferred to stepping "Z" in addition to stepping "PB". The changes are highlighted in the revised status column.

Part Number	Old Stepping (Fab 2)	New Stepping (Fab 4)	Revised Status
IDT74FCT139T	K	KB	Z
IDT74FCT2244T	K	KB	Z
IDT74FCT2245T	K	KB	Z
IDT74FCT2373T	K	KB	Z
IDT74FCT2374T	K	KB	Z
IDT74FCT240T	K, P	PB	PB
IDT74FCT244T	K, P	PB	PB, Z
IDT74FCT245T	K, P	PB	PB, Z
IDT74FCT3244	K	KB	PB, Z
IDT74FCT3245	K	KB	PB, Z
IDT74FCT3573	K	KB	Z



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Part Number	Old Stepping (Fab 2)	New Stepping (Fab 4)	Revised Status
IDT74FCT373T	K, P	PB	PB
IDT74FCT374T	K, P	PB	PB
IDT74FCT377T	K, P	PB	PB
IDT74FCT521	K	KB	Z
IDT74FCT521T	K	KB	PB, Z
IDT74FCT540T	K, P	PB	PB
IDT74FCT573T	K, P	PB	PB
IDT74FCT574T	K, P	PB	PB
IDT74FCT652T	H, P	PB	PB
IDT74FCT823T	H, P	PB	PB
IDT74FCT543T	H, P	PB	PB
IDT49FCT805	K	KB	Z
IDT74FCT157T	P	PB	PB
IDT74FCT257T	P	PB	PB
IDT49FCT3805	P	PB	PB
IDT49FCT805T	P	PB	Z
IDT74FCT3807	P	PB	PB
IDT74FCT807T	P	PB	PB
IDT74FCT162240T	L, LZ	LB	LB
IDT74FCT162244T	Z, L, LZ, LZE	LB	LB
IDT74FCT162245T	L	LB	LB
IDT74FCT162373T	L, LZE	LB	LB
IDT74FCT162374T	L, LZE, Z	LB	LB
IDT74FCT16240T	L	LB	LB
IDT74FCT16244T	L	LB	LB
IDT74FCT16245T	L	LB	LB

Part Number	Old Stepping (Fab 2)	New Stepping (Fab 4)	Revised Status
IDT74FCT162H244T	L	LB	LB
IDT74FCT162H245T	L, LZ	LB	LB
IDT74FCT16373T	L, LZ	LB	LB
IDT74FCT16374T	L, LZ, Z	LB	LB
IDT74FCT166244T	L	LB	LB
IDT74FCT166245T	L	LB	LB
IDT74FST163209	D	DB	DB
IDT74FST163210	D	DB	L-02-04
IDT74FST163211	D	DB	DB
IDT74FST163212	D	DB	DB
IDT74FST163214	D	DB	DB
IDT74FST163232	D	DB	DB
IDT74FST163233	D	DB	DB
IDT74FST1632383	D	DB	DB
IDT74FST163244	D	DB	DB
IDT74FST163245	D	DB	DB
IDT74FST1632861	D	DB	DB
IDT74FST163292	D	DB	L-02-04
IDT74FST163383	D	DB	L-02-04
IDT74FST1632861	D	DB	DB
IDT74FST163P245	D	DB	DB
IDT74FST32XL2384	D	DB	DB
IDT74FST32XL384	D	DB	DB
IDT 74FST6800	F	FB	FB
IDT74FCT162260T	N	NB	NB



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Part Number	Old Stepping (Fab 2)	New Stepping (Fab 4)	Revised Status
IDT74FCT162344T	N	NB	NB
IDT74FCT162500T	N	NB	NB
IDT74FCT162501T	N	NB	NB
IDT74FCT162511T	N	NB	NB
IDT74FCT162543T	N	NB	NB
IDT74FCT162601T	N	NB	NB
IDT74FCT16260T	N, NE	NB	NB
IDT74FCT162646T	N	NB	NB
IDT74FCT162652T	N	NB	NB
IDT74FCT162701T	N	NB	NB
IDT74FCT162823T	N	NB	NB
IDT74FCT162827T	N	NB	NB
IDT74FCT162841T	N	NB	NB
IDT74FCT162952T	N	NB	NB
IDT74FCT162H272T	N	NB	NB

Part Number	Old Stepping (Fab 2)	New Stepping (Fab 4)	Revised Status
IDT74FCT162H501T	N	NB	NB
IDT74FCT162H952T	N	NB	NB
IDT74FCT164245T	N	NB	NB
IDT74FCT16500T	N	NB	NB
IDT74FCT16501T	N	NB	NB
IDT74FCT16543T	N, NE	NB	NB
IDT74FCT16601T	N	NB	NB
IDT74FCT16646T	N	NB	NB
IDT74FCT16652T	N	NB	NB
IDT74FCT16823T	N	NB	NB
IDT74FCT16827T	N	NB	NB
IDT74FCT16841T	N	NB	NB
IDT74FCT16952T	N	NB	NB
IDT74FCT388915T	N	NB	NB
IDT74FCT88915TT	N	NB	NB

Qualification Plans: Following reliability tests were performed per product family and the qualification test results are as follows:

	Required Sample/ # Fails	Qual Test Results Sample/ # Fails
Operating Life Test: Dynamic (1000 hrs @ 125°C or equivalent)	116/0	116/0
Bake & Ballshear Test (@ 200°C / 4 ball bonds per device)	5/0	5/0
Temperature Cycling: (-65°C to +150°C, 500 cycles)	45/0	45/0
HAST: (Biased, 100 Hrs. @ +130°C, +85%RH)	45/0	45/0
ESD Human Body Model	3/0	3/0
ESD Charged Device Model	3/0	3/0
ESD Machine Model	3/0	3/0
Latch up: (Tested to 1.5X Vcc)	10/0	10/0

Characterization Data:
Characterization data is available upon request.